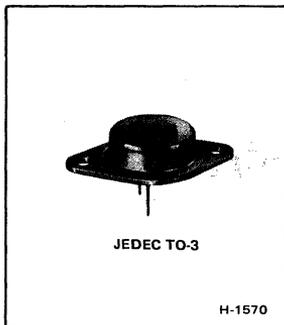


RCA
Solid State
Division

Power Transistors

RCS564



300-V, 30-A, 175-W Silicon N-P-N Switching Transistor

For Switching Applications in
Industrial and Commercial Equipment

Features:

- High voltage ratings:
 $V_{CBO} = 300\text{ V}$
- Maximum safe-area-of-operation curves
- High dissipation rating: $P_T = 175\text{ W}$
- Low saturation voltages

The RCA-RCS564 is a multiple epitaxial silicon n-p-n power transistor utilizing a multiple-emitter-site structure. Multiple-epitaxial construction maximizes the volt-ampere characteristic of the device and provides fast switching speeds. Multiple-emitter-site design assures uniform current flow throughout the structure, which produces a high I_S/b and a large safe-operation area.

The device uses the popular JEDEC TO-3 package.

The exceptional second-breakdown capabilities and high voltage-breakdown ratings of the RCS564 make this transistor especially suitable for off-line inverters, switching regulators, motor controls, and deflection circuit applications.

The high gain and high E_S/b energy-handling capability of the RCS564 make it an excellent choice for motor-control applications in which large winding inductances are encountered and high surge currents are required to start the motor.

MAXIMUM RATINGS, Absolute-Maximum Values:

COLLECTOR-TO-BASE VOLTAGE	V_{CBO}	300	V
COLLECTOR-TO-EMITTER SUSTAINING VOLTAGE:			
With base open	$V_{CE0(sus)}$	200	V
With reverse bias ($V_{BE} = 0\text{ V}$ (with base-emitter shorted))	$V_{CEX(sus)}$	225	V
With external base-to-emitter resistance ($R_{BE} \leq 50\ \Omega$)	$V_{CER(sus)}$	225	V
EMITTER-TO-BASE VOLTAGE	V_{EBO}	6	V
CONTINUOUS COLLECTOR CURRENT	I_C	10	A
PEAK COLLECTOR CURRENT	I_{CM}	30	A
CONTINUOUS BASE CURRENT	I_B	10	A
TRANSISTOR DISSIPATION:	P_T		
At case temperatures up to 25°C and V_{CE} up to 30 V		175	W
At case temperatures up to 25°C and V_{CE} above 30 V			See Figs. 1 and 2.
At case temperatures above 25°C and V_{CE} above 30 V			See Figs. 1, 2, and 4.
TEMPERATURE RANGE:			
Storage & Operating (Junction)		-65 to +200	$^\circ\text{C}$
PIN TEMPERATURE (During Soldering):			
At distances $\geq 1/32\text{ in.}$ (0.8 mm) from case for 10 s max.		230	

ELECTRICAL CHARACTERISTICS, At Case Temperature (T_C) = 25°C unless otherwise specified

CHARACTERISTIC	SYMBOL	TEST CONDITIONS				LIMITS			UNITS
		VOLTAGE V dc		CURRENT A dc		RCS564			
		V_{CE}	V_{BE}	I_C	I_B	Min.	Typ.	Max.	
Collector-Cutoff Current: With base open	I_{CEO}	150			0	—	—	10	mA
With base-emitter junction reverse-biased	I_{CEV}	225	-1.5			—	—	10	
With base-emitter junction reverse-biased, and $T_C = 125^\circ\text{C}$	I_{CEV}	225	-1.5			—	—	25	
Emitter-Cutoff Current	I_{EBO}		-6			—	—	5	mA
Collector-to-Emitter Sustaining Voltage (see Figs. 11 and 12): With base open	$V_{CEO(sus)}$			0.2		200 ^b	—	—	V
With external base-to-emitter resistance (R_{BE}) = 50 Ω	$V_{CER(sus)}$			0.2		225 ^b	—	—	V
DC Forward-Current Transfer Ratio	h_{FE}	3		10 ^a		5	—	—	
Base-to-Emitter Saturation Voltage	$V_{BE(sat)}$			10 ^a	2	—	—	3.2	V
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$			10 ^a		—	—	2.5	V
Magnitude of Common Emitter, Small-Signal, Short-Circuit, Forward Current Transfer Ratio: $f = 1$ MHz	$ h_{fe} $	10		1		2.5	8	—	
Second-Breakdown Collector Current: $t = 1$ s, nonrepetitive	$I_{S/b}^c$	30				5.8	—	—	A
Reverse-Bias Second-Breakdown Energy: $R_B = 50 \Omega$, $L = 50 \mu\text{H}$	$E_{S/b}^d$		-4	10		2.5	—	—	mJ
Switching Times ($V_{CC} = 200$ V): ^e									μs
Rise Time	t_r			10	1	—	0.8	2	
Storage Time	t_s			10	1	—	1.8	3.5	
Fall Time	t_f			10	1	—	0.5	1	
Thermal Resistance: Junction-to-Case	$R_{\theta JC}$	10		5	—	—	—	1	$^\circ\text{C/W}$

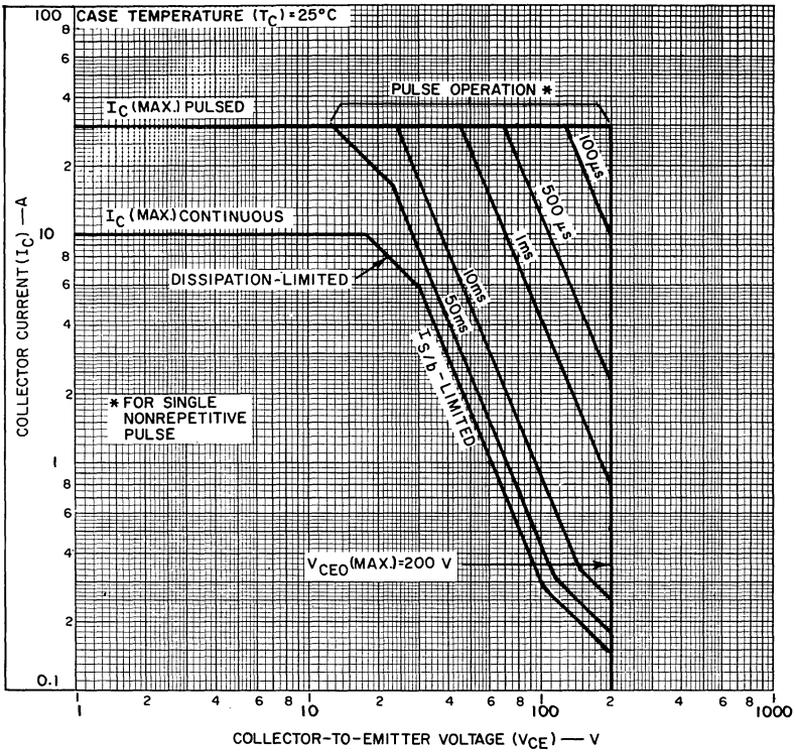
^aPulses; pulse duration $\leq 350 \mu\text{s}$, duty factor = 2%.

^bCAUTION: The sustaining voltages $V_{CEO(sus)}$ and $V_{CER(sus)}$ MUST NOT be measured on a curve tracer. These sustaining voltages should be measured by means of the test circuit shown in Fig. 11.

^c $I_{S/b}$ is defined as the current at which second breakdown occurs at a specified collector voltage with the emitter-base junction forward-biased for transistor operation in the active region.

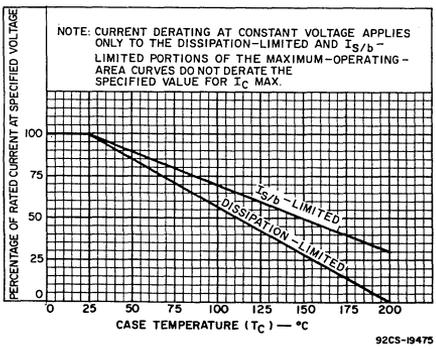
^d $E_{S/b}$ is defined as the energy at which second breakdown occurs under specified reverse-bias conditions. $E_{S/b} = 1/2 LI^2$ where L is a series load or leakage inductance, and I is the peak collector current.

^e $I_{B1} = I_{B2}$ = value shown: see Figs. 13 – 18.



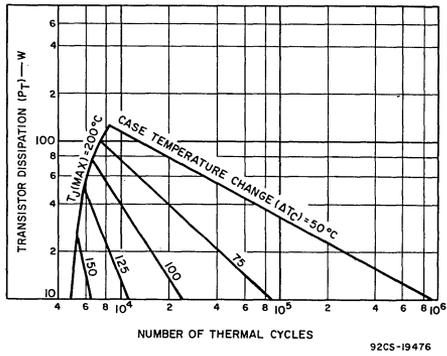
92CS-24683

Fig. 1 - Maximum operating areas.



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Fig. 2 - Dissipation derating and $I_{S/b}$ derating.



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Fig. 3 - Thermal-cycle rating chart.

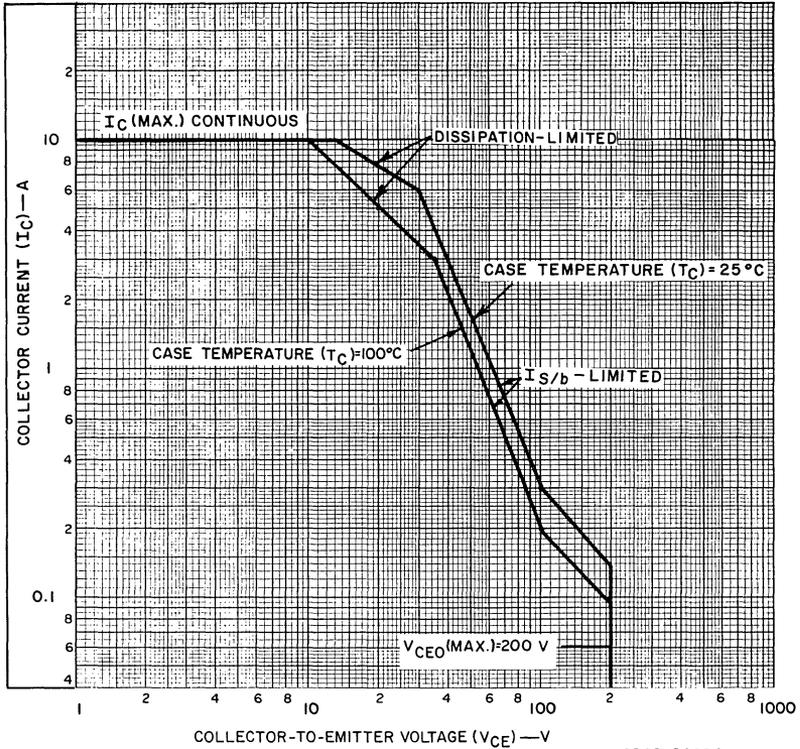


Fig. 4 - Maximum operating areas for dc operation at $T_C = 25^\circ\text{C}$ and 100°C .

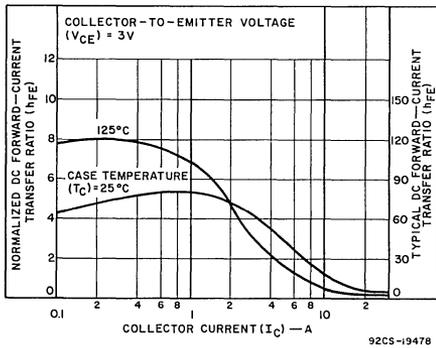


Fig. 5 - Typical normalized dc beta characteristics.

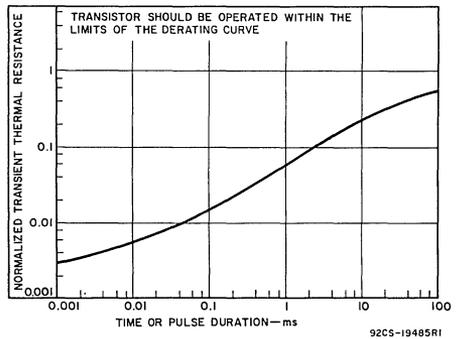


Fig. 6 - Typical thermal response characteristic.

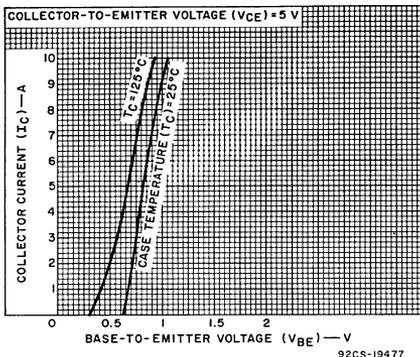


Fig. 7 - Typical transfer characteristics.

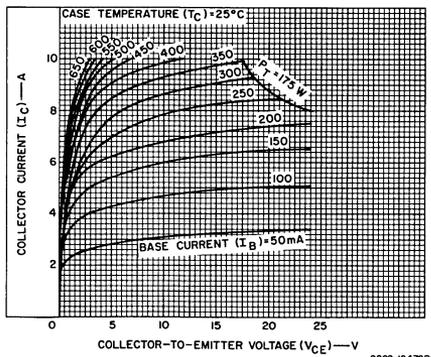


Fig. 8 - Typical output characteristics.

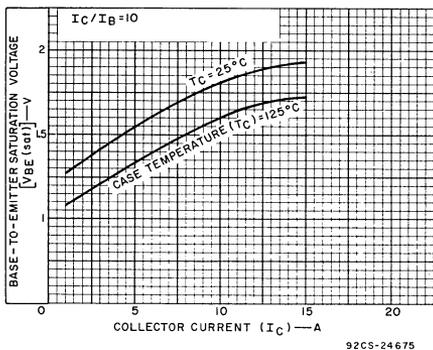


Fig. 9 - Typical base-to-emitter saturation voltage characteristics.

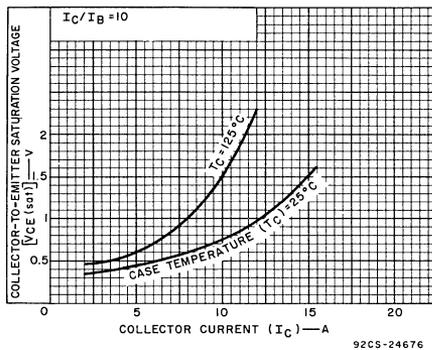


Fig. 10 - Typical collector-to-emitter saturation voltage characteristics.

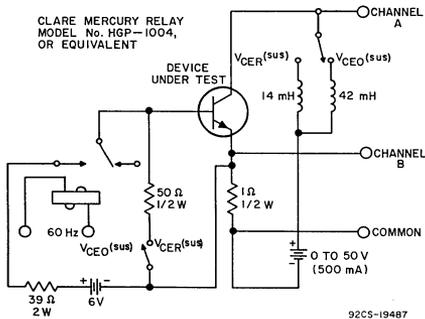
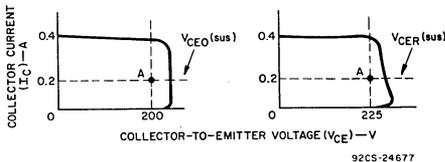


Fig. 11 - Circuit used to measure sustaining voltages $V_{CE0}(sus)$ and $V_{CER}(sus)$.



The sustaining voltages $V_{CE0}(sus)$ and $V_{CER}(sus)$ are acceptable when the traces fall to the right of point "A".
 Fig. 12 - Oscilloscope display for measurement of sustaining voltages. (Test circuit shown in Fig. 11).

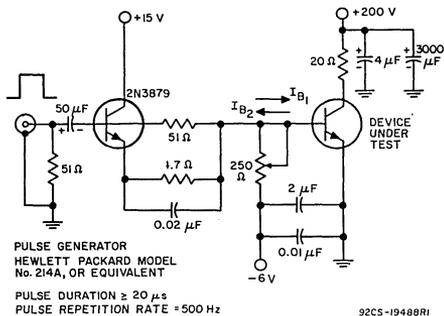


Fig. 13 - Circuit used to measure switching times.

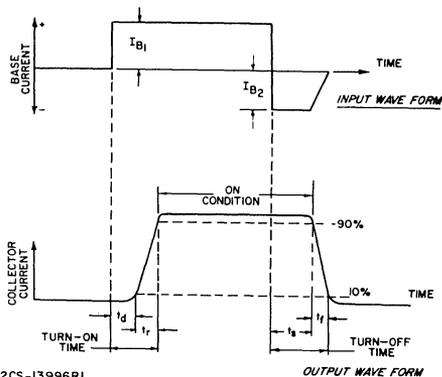


Fig. 14 - Phase relationship between input and output currents showing reference points for specification of switching times. (Test circuit shown in Fig. 13).

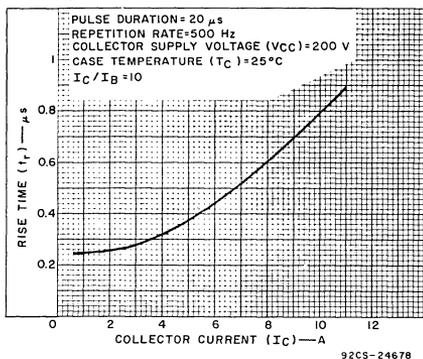


Fig. 15 - Typical rise-time characteristic.

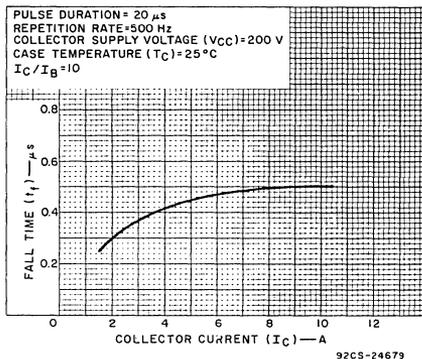


Fig. 16 - Typical fall-time characteristic.

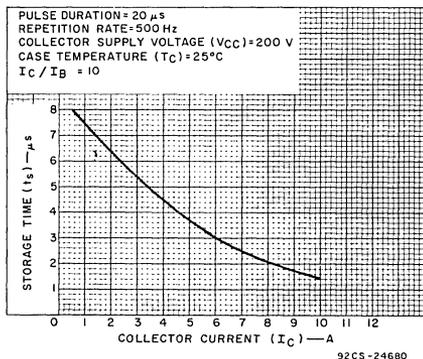


Fig. 17 - Typical storage-time characteristics for all types (with constant forced gain).

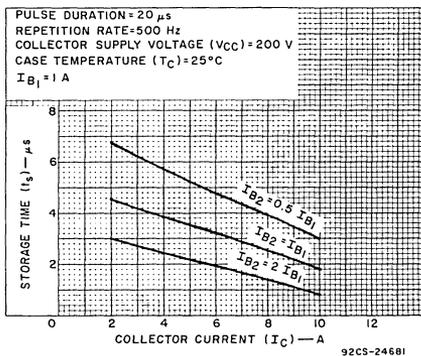


Fig. 18 - Typical storage-time characteristics for all types (with constant base drive).

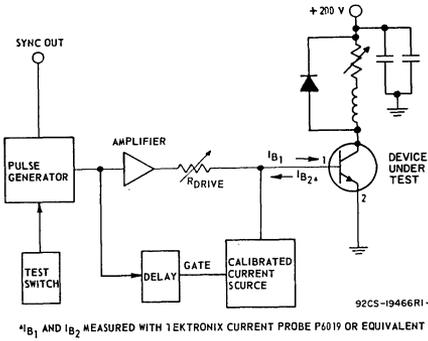


Fig. 19 — Circuit used to measure inductive-load switching times.

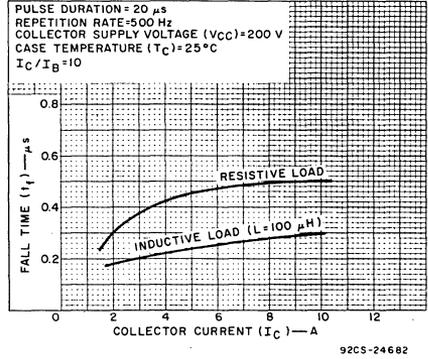


Fig. 20 — Typical inductive- and resistive-load fall-time characteristics.

TERMINAL CONNECTIONS

- Pin 1 — Base
- Pin 2 — Emitter
- Case — Collector
- Mounting Flange — Collector